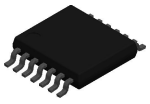
DATA BOOK
PACKAGE OUTLINE

DRAFTER: K. SINCERBOX	DATE: 06/01/2023		DIMENSIONS IN MILLIMETERS
DESIGNER:	DATE:	TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS	CODE IDENTITY NUMBER 01295
CHECKER: ANIS FAUZI	DATE: 12/11/2023		
ENGINEER: EUGENE LEE	DATE: 12/11/2023	ePOD, PWP0014K / HTSSOP 14 PIN, 0.65 MM PITCH	
APPROVED: K. SINCERBOX & D. CHIN	DATE: 12/11/2023		
RELEASED: NAZRIN CHU	DATE: 12/11/2023		
TEMPLATE INFO: EDGE# 4218519	DATE: 04/07/2016	SCALE NTS / SIZE A / 4229706 / REV B / PAGE 1 OF 5	

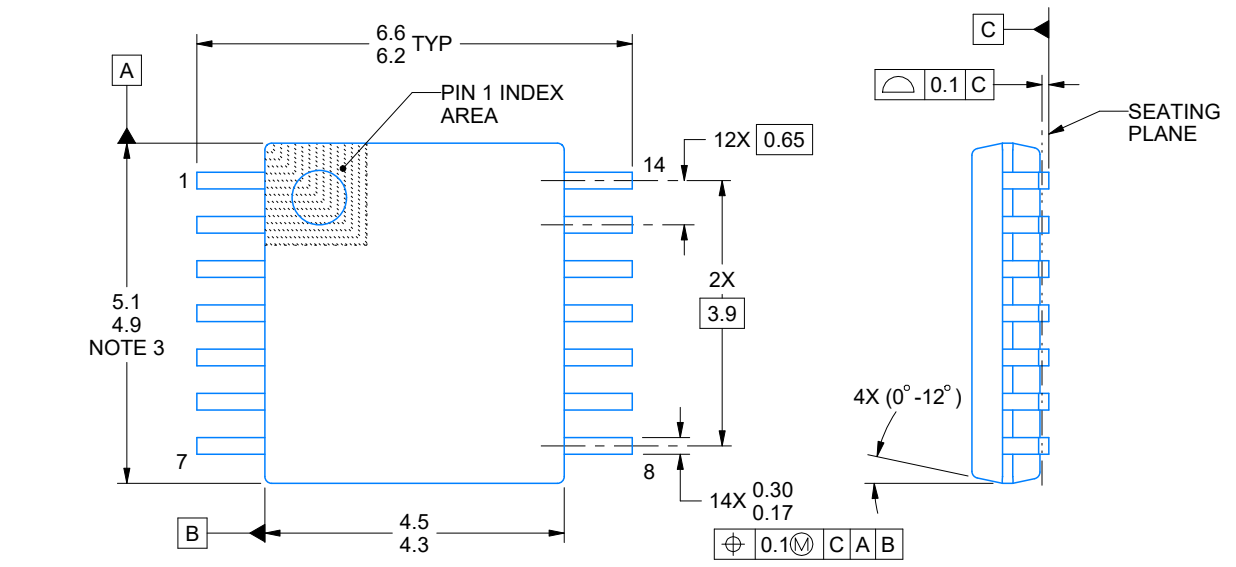
PACKAGE OUTLINE

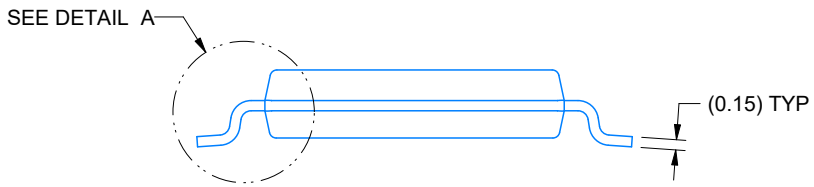
PWP0014K

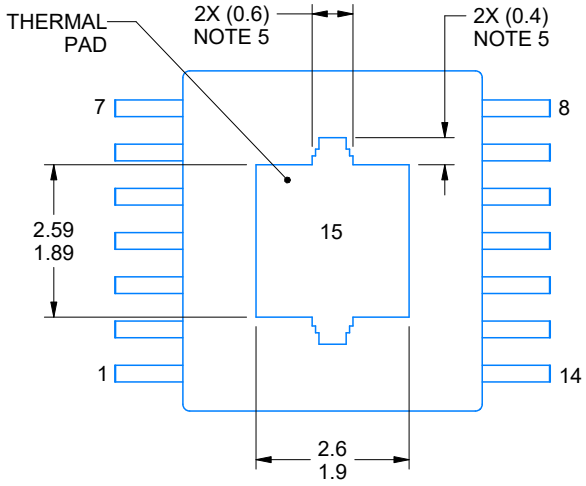


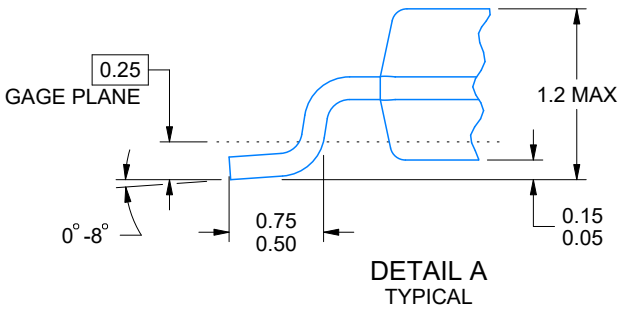
PowerPAD™ TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE









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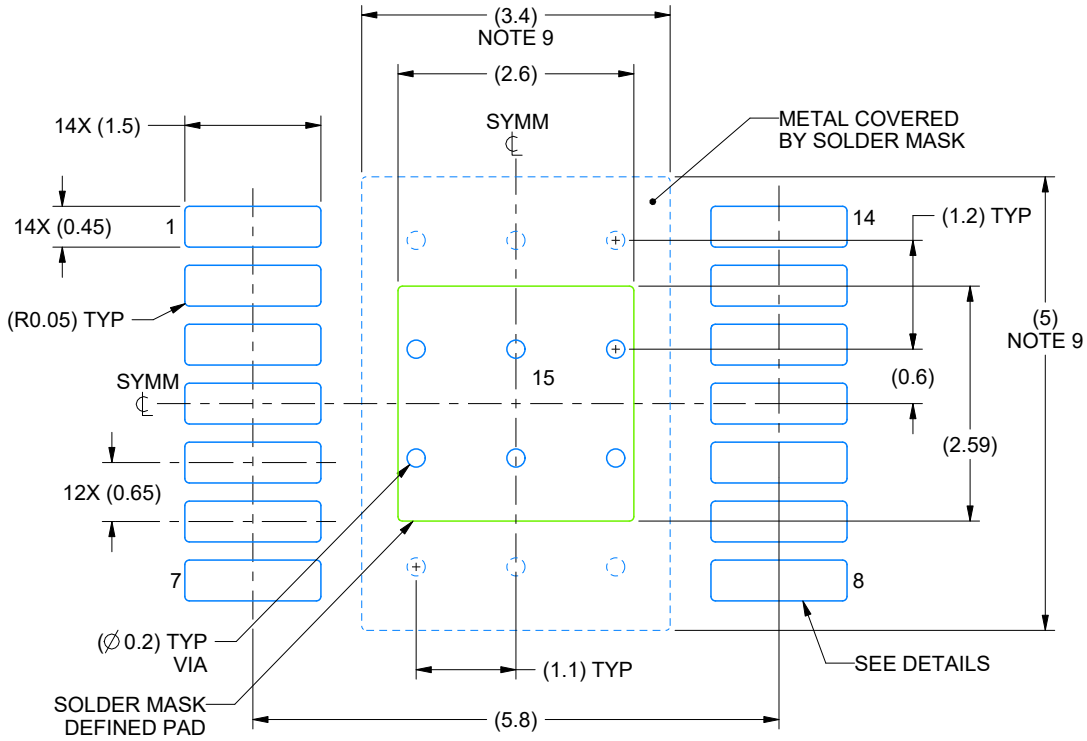
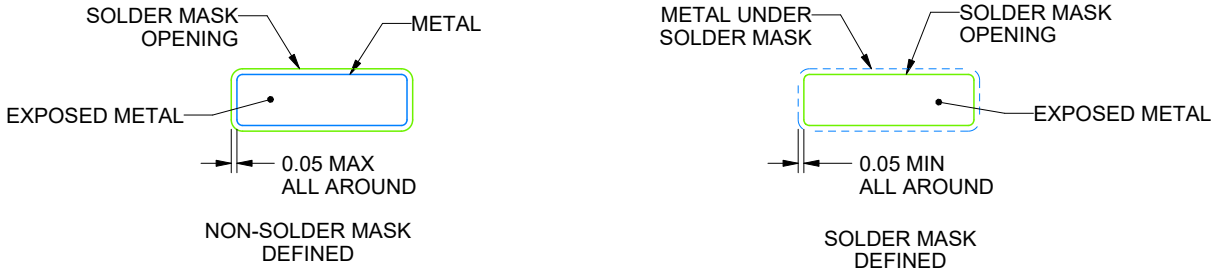
PowerPAD is a trademark of Texas Instruments.

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.
5. Features may differ or may not be present.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 12X



SOLDER MASK DETAILS

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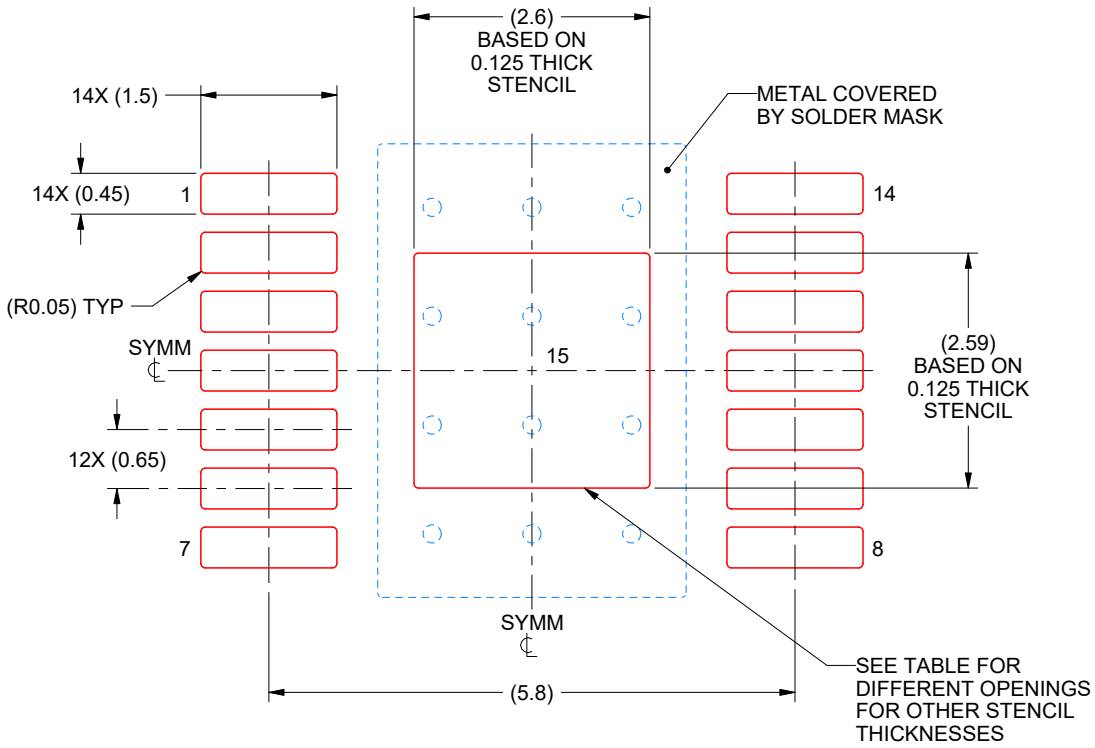
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 12X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	2.91 X 2.90
0.125	2.60 X 2.59 (SHOWN)
0.15	2.37 X 2.36
0.175	2.20 X 2.19

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NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2204487	06/01/2023	F. HE / K. SINCERBOX
B	UPDATE LEAD WIDTH SPEC & BODY DRAFT ANGLE	2206688	12/11/2023	EUGENE LEE / NAZRIN CHU